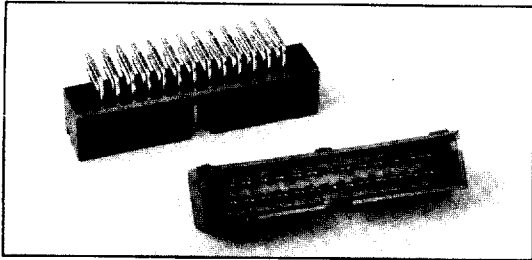


Low Profile Headers .025" sq. Post

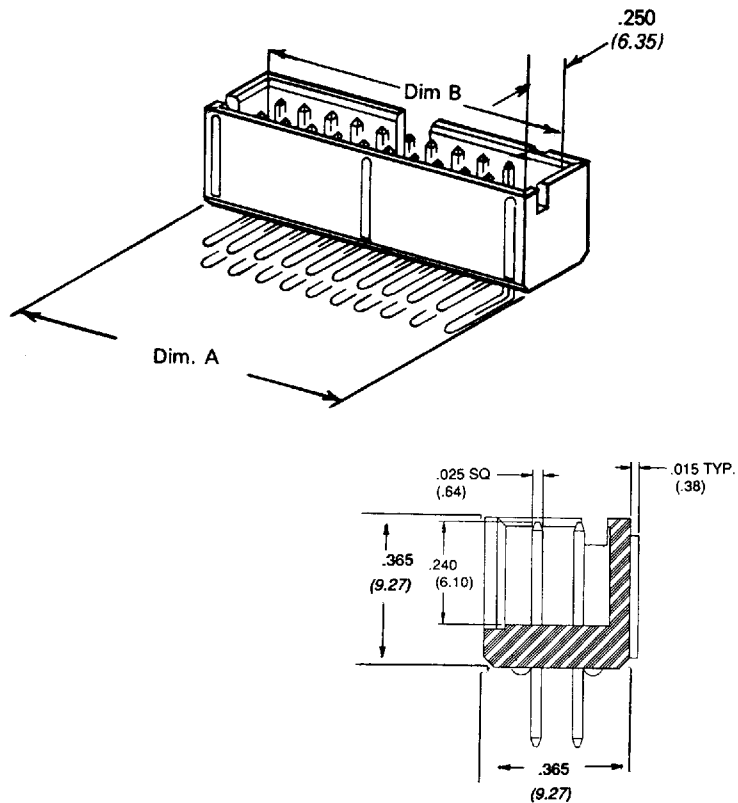
IDH-LP Series



- Designed for applications where space is critical
- Fool-proof socket polarization
- Optional ROBEX® better-than-gold plating

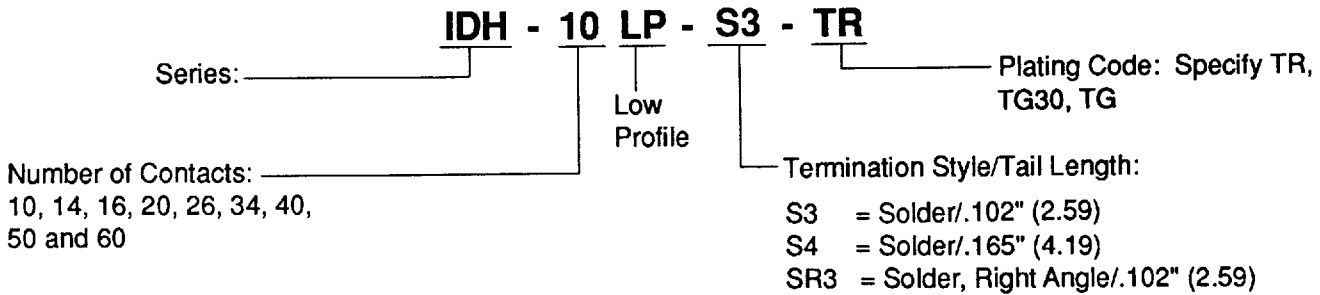
For Recommended PC Board Layout See Page 351.

Tabulations			
No. of Contacts	Dim. A Inches (mm)	Dim. B Inches (mm)	Dim. C Inches (mm)
10	.800 (20.32)	.700 (17.78)	.400 (10.16)
14	1.000 (25.40)	.900 (22.86)	.600 (15.24)
16	1.100 (27.94)	1.000 (25.40)	.700 (17.78)
20	1.300 (33.02)	1.200 (30.48)	.900 (22.86)
26	1.600 (40.64)	1.500 (38.10)	1.200 (30.48)
34	2.000 (50.80)	1.900 (48.26)	1.600 (40.64)
40	2.300 (58.42)	2.200 (55.88)	1.900 (48.26)
50	2.800 (71.12)	2.700 (68.58)	2.400 (60.96)
60	3.300 (83.82)	3.200 (81.28)	2.900 (73.66)



IDC CABLE-TO-BOARD


How to Order IDH-LP Series




Materials:

Body: Glass-filled, black polyester
Contact: Phosphor Bronze

Agency Approvals:

 #E73746

 #46898

Performance

Characteristics:

Temperature Range: -55°C to + 105°C
Contact Resistance: 20 Milliohms Max.
Insulation Resistance: 5000 Megaohms Min.
Dielectric Withstand Voltage: 500 volts DC
Current Rating: 1 Ampere at 25°C ambient
Flammability: UL 94V-0

Plating Description:

Suffix TR = 10 μinch (.254 μm) minimum
ROBEX® on contact area.
100 μinch (2.54 μm) minimum
Tin on terminal area.

TG30 = 30 μinch (.762 μm) minimum
Gold on contact area.
100 μinch (2.54 μm) minimum
Tin on terminal area.

TG = 10 μinch (.254 μm) minimum
Gold on contact area.
100 μinch (2.54 μm) minimum
Tin on contact area.

All options include an underplate of 50 μinch
(1.27 μm) minimum Nickel.

IDC Product Specifications and Test Data

Electrical

Current Rating	1 Amp
Insulation Resistance	>5 X 10 ⁹ Ohms at 500 VDC
Withstanding Voltage	500 VRMS at Sea Level
Contact Resistance	20 milliohms Maximum

Environmental

Operating Temperature	
Phos Bronze Contacts	-55°C to + 105°C
Be Cu Contacts	-55°C to + 125°C
Corrosive Atmosphere	
Ammonium Polysulfate (4 Hours)	R _C = 9.3 milliohms
Nitric Acid (1 Hour)	R _C = 8.4 milliohms
Salt Spray	
MIL-STD-1344, Method 1001, Condition B	R _C - 11.7 milliohms
+ 35°C, 96 Hours	(no damage)
Humidity	
MIL-STD-1344, Method 1002, Type I, Condition B	R _C = 14.8 milliohms
96 Hours, 95% Relative Humidity, + 40°C	(no damage)
Thermal Shock	
MIL-STD-1344, Method 1003, Condition A	R _C - 11.7 milliohms
-55°C to + 85°C (5 Cycles)	(no damage)
Mechanical Shock	
MIL-STD-1344, Method 2004, Condition G	No Discontinuity
100 Gs, 6 milliSeconds Each Axis	
Vibration	
MIL-STD-1344, Method 2005, Condition 4	No Discontinuity
10-2000 Hz, 20 G Peak (12 Cycles)	
Temperature Life	
MIL-STD-1344, Method 1005, 1,000 Hours, Condition 4	R _C - 14.9 milliohms
+ 105°C	
Socket Durability	
500 Cycles	R _C = <12 milliohms

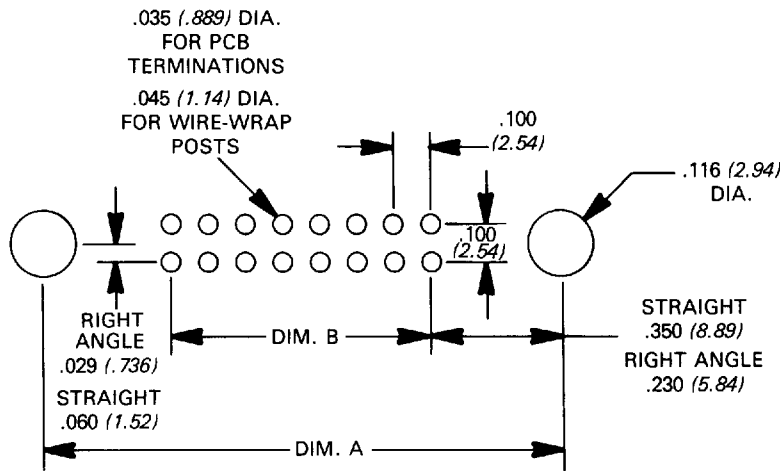
Note: For Complete test results on high reliability ROBEX® plating (TR and TR30), contact the factory.

IDC
CABLE-TO-BOARD

.025" Sq. Post Headers

The detail below describes the recommended mounting hole patterns and hole sizes for the following post leader series: IDH-PK, IDH-K, IDH-LP.

Note: The mounting hole information will apply to IDH-PK and IDH-K Series only.



Inches (mm)

No. of Contacts	Dim. A for Straight Mount	Dim. A for Right Angle Mount	Dim. B
10	1.100 (27.94)	.860 (21.84)	.400 (10.16)
14	1.300 (33.02)	1.060 (26.92)	.600 (15.24)
16	1.400 (35.56)	1.160 (29.46)	.700 (17.78)
20	1.600 (40.64)	1.360 (34.54)	.900 (22.86)
26	1.900 (48.26)	1.660 (42.16)	1.200 (30.48)
34	2.300 (58.42)	2.060 (52.32)	1.600 (40.64)
40	2.600 (66.04)	2.360 (59.94)	1.900 (48.26)
50	3.100 (78.74)	2.860 (72.64)	2.400 (60.96)
60	3.600 (91.44)	3.360 (85.34)	2.900 (73.66)

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CABLE-TO-BOARD